

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5014601

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jen-Chieh Lin	06/08/2018
Wen-Chin Lin	06/08/2018
Chi-Lune Huang	06/08/2018
Pi-Hung Chuang	06/08/2018
Tai-Lin Chen	06/08/2018
Sun-Hong Chen	06/08/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>Name:</b>	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
<b>Street Address:</b>	NO.88, LIANHUA AVENUE, INTEGRATED CIRCUIT SCIENCE PARK, JINJIANG CITY
<b>City:</b>	QUANZHOU CITY, FUJIAN PROVINCE
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15904405
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	3027291562
<b>Email:</b>	Patent.admin.uspto.cr@naipo.com
<b>Correspondent Name:</b>	WINSTON HSU
<b>Address Line 1:</b>	5F., NO.389, FUHE RD., YONGHE DIST.,
<b>Address Line 4:</b>	NEW TAIPEI CITY, TAIWAN
<b>ATTORNEY DOCKET NUMBER:</b>	NAUP2974USA
<b>NAME OF SUBMITTER:</b>	KATE YEH

<b>SIGNATURE:</b>	/KATE YEH/
<b>DATE SIGNED:</b>	06/20/2018
<b>Total Attachments: 14</b> source=3178389#page1.tif source=3178389#page2.tif source=3178389#page3.tif source=3178389#page4.tif source=3178389#page5.tif source=3178389#page6.tif source=3178389#page7.tif source=3178389#page8.tif source=3178389#page9.tif source=3178389#page10.tif source=3178389#page11.tif source=3178389#page12.tif source=3178389#page13.tif source=3178389#page14.tif	

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**  
**PLANARIZATION METHOD**

As the below named inventor, I hereby declare that:  
This declaration is directed to:

- The attached application, or
- United States application number 15/904,405 filed on 02/25/2018, or
- PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

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(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

In consideration of the payment by **Fujian Jinhua Integrated Circuit** having a postal address of **Co., Ltd.**

**No.88, Lianhua Avenue, Integrated Circuit Science Park, Jinjiang City, Quanzhou City, Fujian Province 362200, P.R.C.**

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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

Docket No NAUP2974USA

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.  
IN WITNESS WHEREOF, I have hereunto set hand and seal this JUN 08 2018 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Jen-Chieh Lin

Date: JUN 08 2018

Signature: 

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Lee-Yuan Chen**

Date: \_\_\_\_\_

Signature: \_\_\_\_\_

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Wen-Chin Lin Date: JUN 08 2018  
Signature: Wen-Chin Lin



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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chi-Lune Huang**

Date: **JUN 08 2018**

Signature: Chi-Lune Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Pi-Hung Chuang**

Date: **JUN 08 2018**

Signature:

Pi-Hung Chuang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tai-Lin Chen**

Date: **JUN 08 2018**

Signature: Tai-Lin Chen

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Signature: Sun - Hong Chen

NPO#NAU-P2974-USA:0  
CUST#UMCF-2016-0181

Page 14 of 14

F#NPO-P0002E-US1201  
DSB0-106U036473

RECORDED: 06/20/2018

PATENT  
REEL: 046135 FRAME: 0193